Epoxy Bond 550

Technical Data Sheet

Epoxy Bond 550 is an epoxy adhesive designed to be used in applications where high temperatures and strong chemicals will be encountered. Not only does it have a very high heat deflection temperature, it has proven to bond extremely well to a wide variety of surfaces. While it will harden at room temperature it requires a bake cure to achieve full properties. Its extremely high physical properties and bond strengths to most surfaces make it applicable for filament winding, resin transfer molding, compression molding and tooling manufacture. As a casting resin it works well potting electrical and other industrial components.

LIQUID PROPERTIES

Property	Unit	Value
Mix ratio by Volume		4:1
Hardener viscosity	cps	3,000
Epoxy viscosity	cps	14,000
Mixed viscosity	cps	6,300
Pot life @ 25°C	min	195

CURE SCHEDULE

Cure Schedule		2 hours @ 176°F/80°C
	followed by	3 hours @ 300°F/146°C
Or		.5 hours @ 176°F/80°C
	followed by	1-2 hours @ 338°F/170°C

CURED STATE PROPERTIES

Property	Unit	Value
Heat deflection temperature	°F/°C	324/162
Tensile strength	psi	10,500
Tensile modulus	psi	388,000
Tensile elongation at break	%	4.9
Flexural strength	psi	19,500
Flexural modulus	psi	500,000

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